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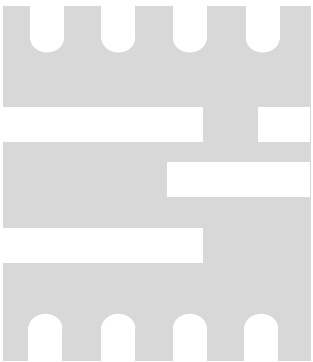
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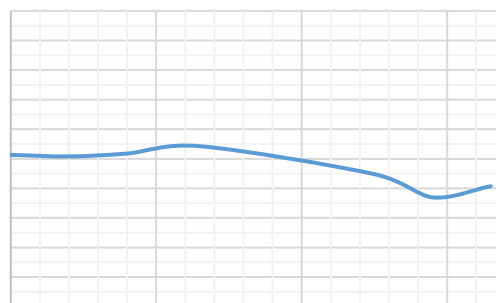
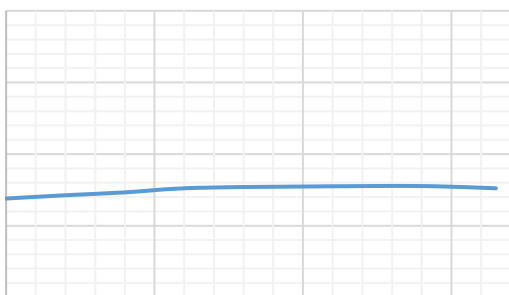
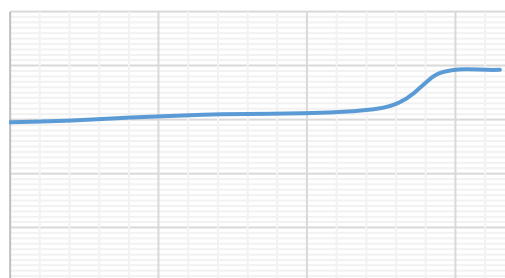
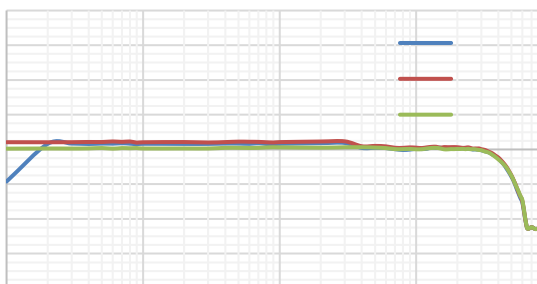
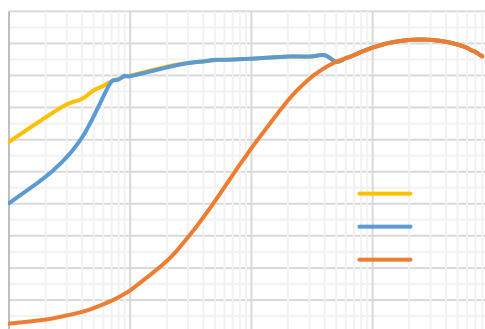
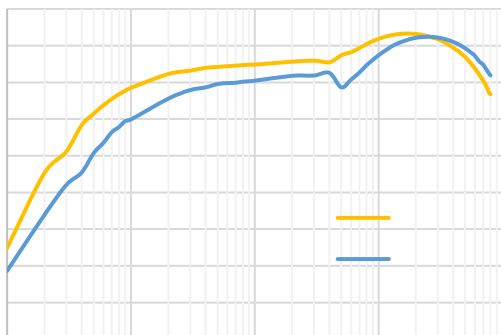
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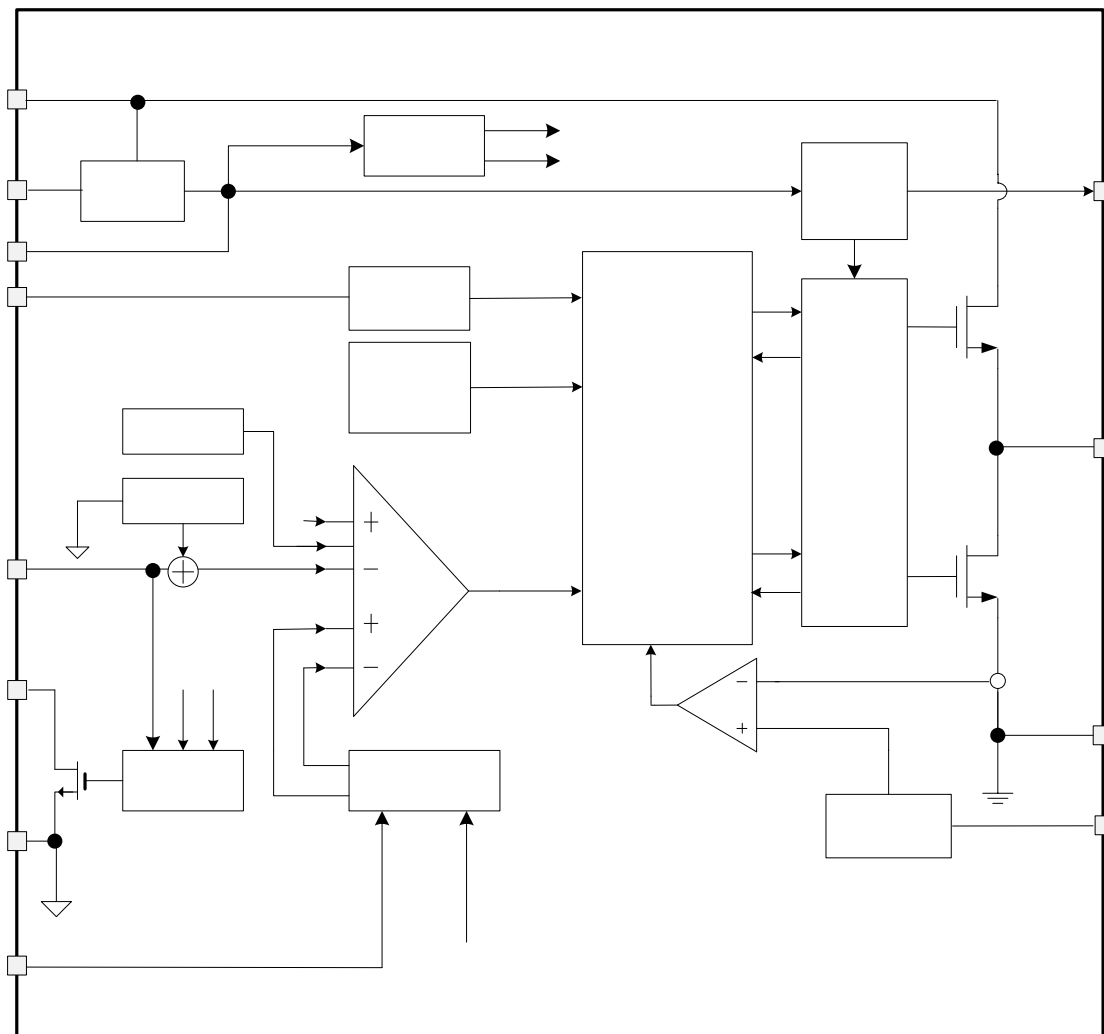
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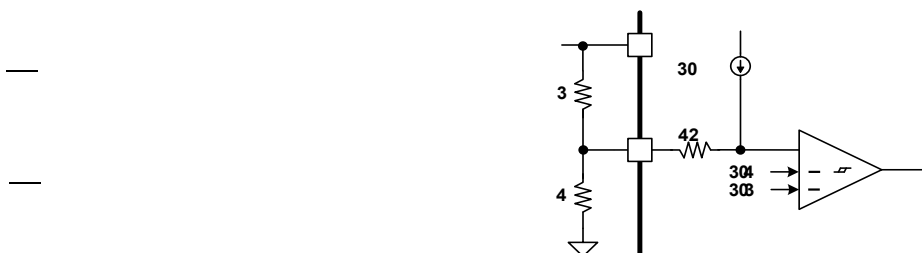
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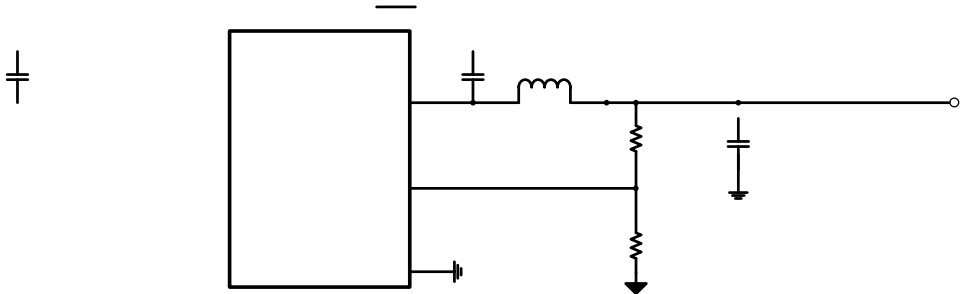
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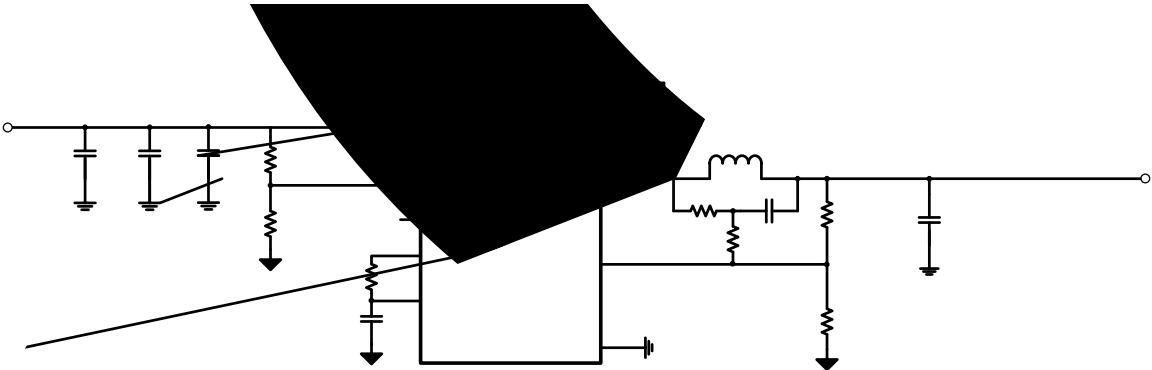
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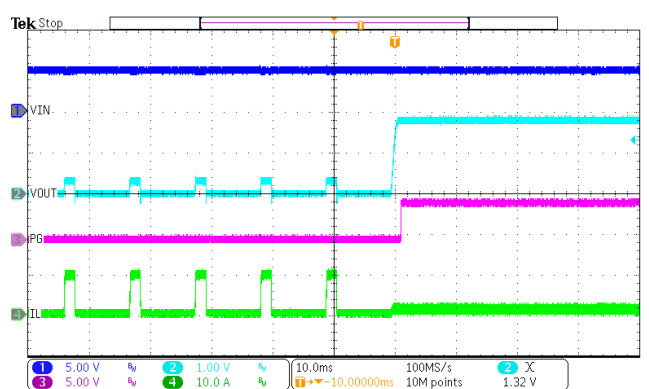
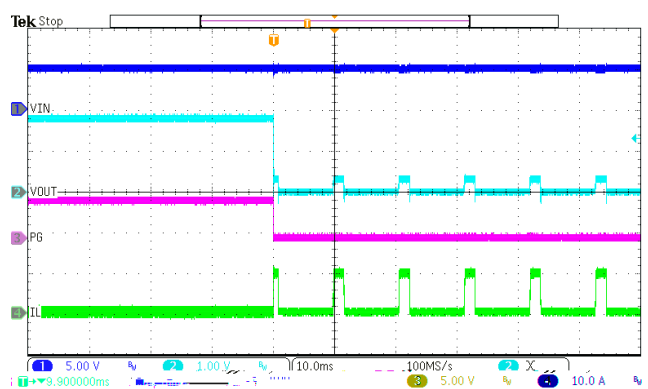
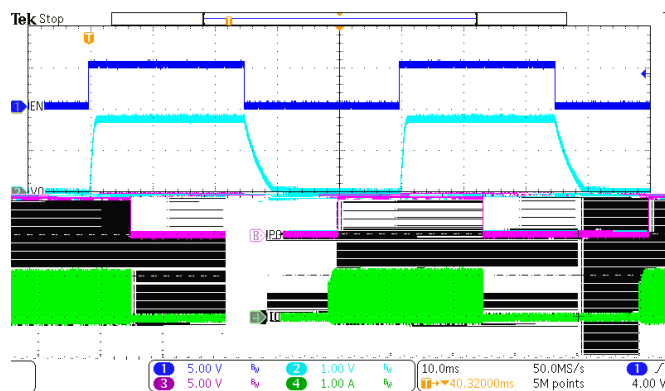
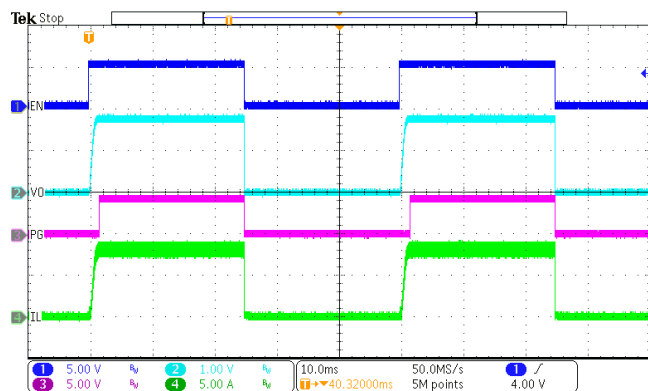
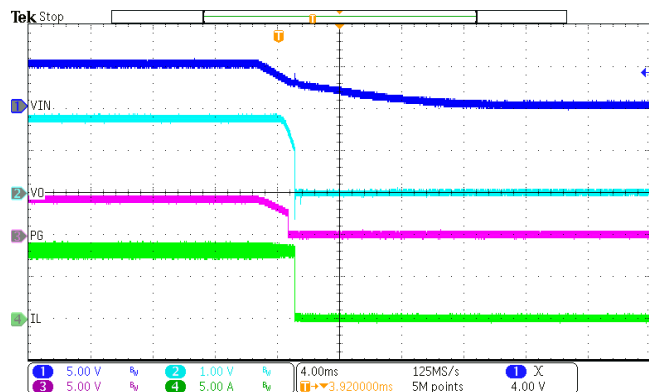
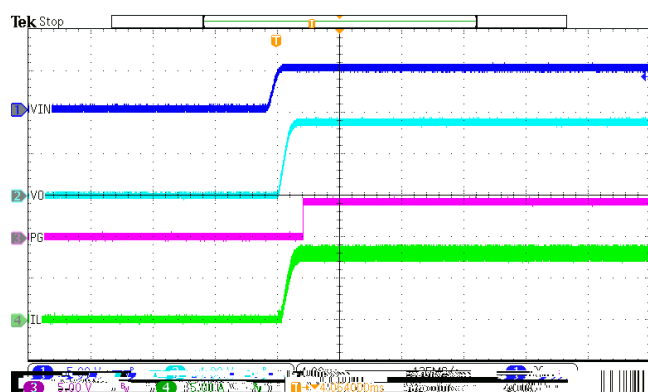
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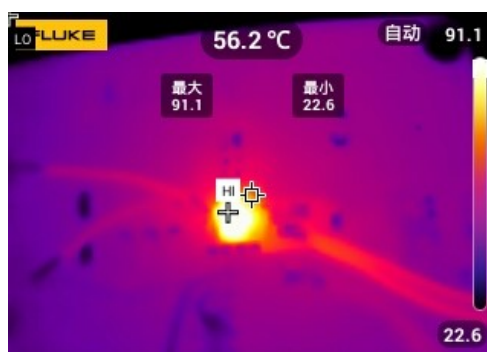
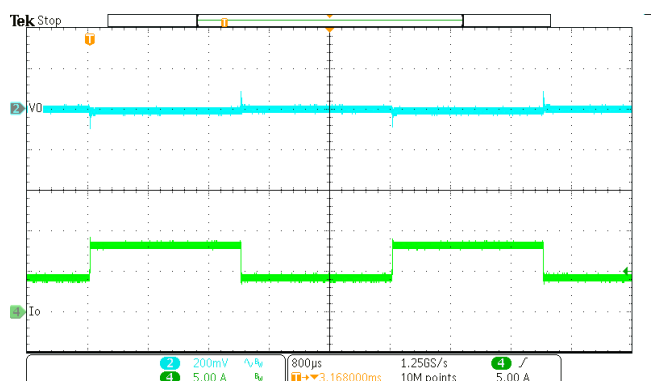
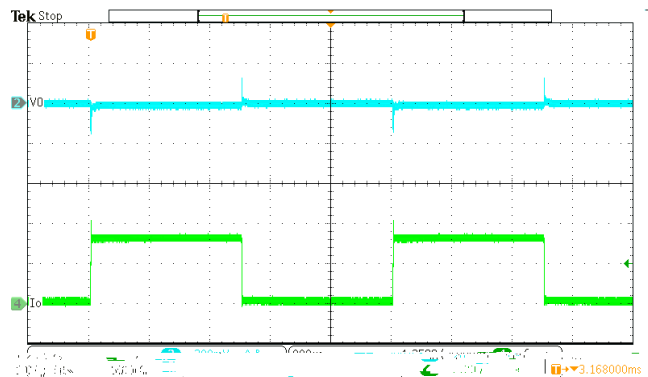
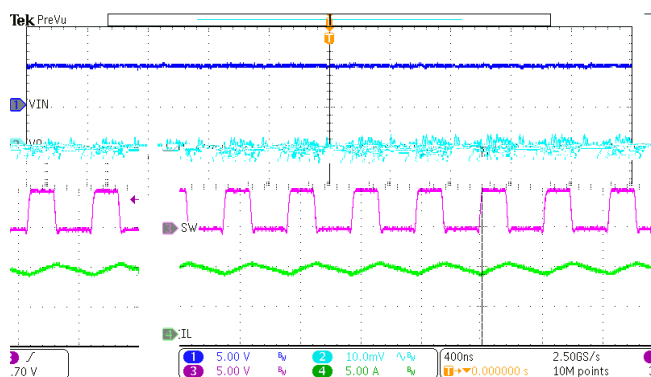
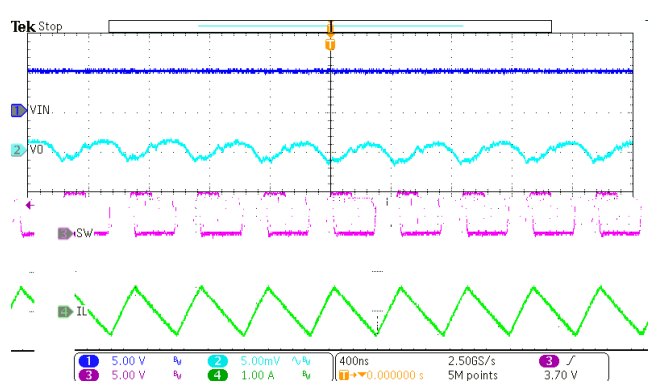
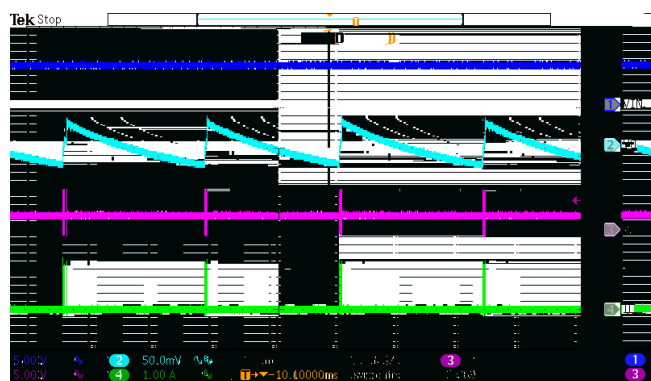




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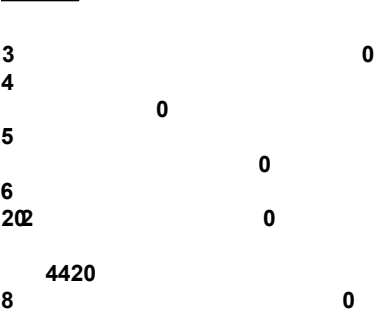
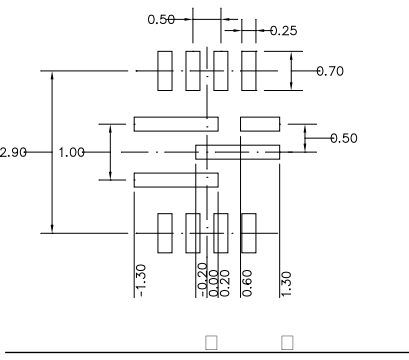
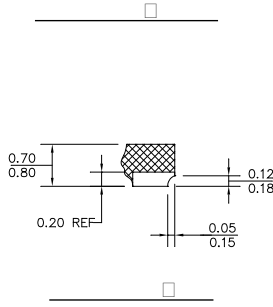
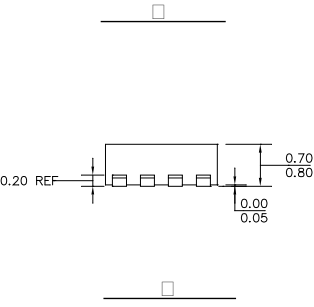
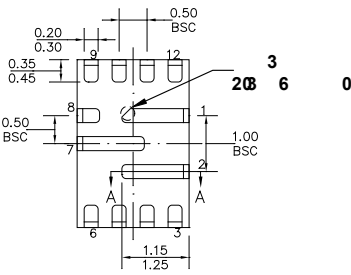
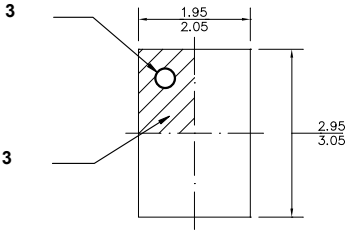






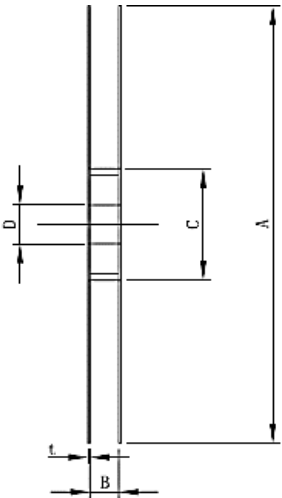
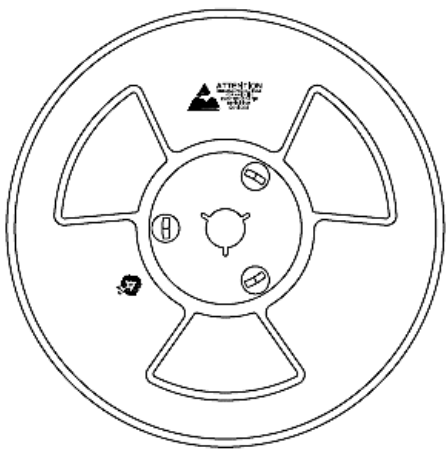
The bottom layer is a large ground plane connected to the ground plane on top layer by vias. It is recommended 8mil diameter drill holes of thermal vias, but a smaller via offers less risk of solder volume loss. On applications where solder volume loss through the vias is of concern, plugging or tenting can be used to achieve a repeatable process.

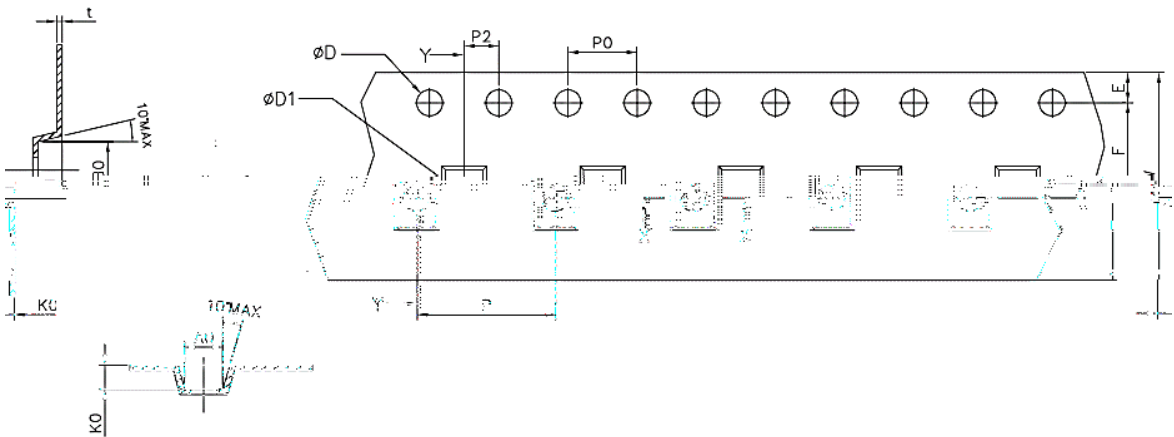
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